

Silicon PIN Photodiode



DESCRIPTION

VEMD1160X01 is a high speed and high sensitive PIN photodiode with a highly linear photoresponse. It is a low profile surface mount device (SMD) including the chip with a 0.23 mm² sensitive area and a daylight blocking filter.

FEATURES

- Package type: surface mount
- Package form: 0805 top view
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- Radiant sensitive area (in mm²): 0.23
- Daylight blocking filter
- AEC-Q101 qualified
- High photo sensitivity
- High radiant sensitivity
- Excellent I_{ra} linearity
- Fast response times
- Angle of half sensitivity: $\phi = \pm 70^\circ$
- Floor life: 72 h, MSL 4, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

 AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

APPLICATIONS

- High speed photo detector
- Small signal detection
- Proximity sensors

PRODUCT SUMMARY

COMPONENT	I _{ra} (μA)	φ (deg)	λ _{0.1} (nm)
VEMD1160X01	1.8	± 70	700 to 1070

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMD1160X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805 top view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	20	V
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW
Junction temperature		T _j	110	°C
Operating temperature range		T _{amb}	-40 to +110	°C
Storage temperature range		T _{stg}	-40 to +110	°C
Soldering temperature	According to reflow solder profile Fig. 6	T _{sd}	260	°C
Thermal resistance junction / ambient	According to EIA / JESD 51	R _{thJA}	270	K/W

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 50\text{ mA}$	V_F	-	0.9	1.1	V
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$, $E = 0$	$V_{(BR)}$	20	-	-	V
Reverse dark current	$V_R = 10\text{ V}$, $E = 0$	I_{r0}	-	0.01	5	nA
Diode capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D	-	3.8	-	pF
	$V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D	-	1.8	-	pF
Open circuit voltage	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	V_o	-	350	-	mV
Temperature coefficient of V_o	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	TK_{V_o}	-	-2.6	-	mV/K
Short circuit current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	I_k	-	1.8	-	μA
Temperature coefficient of I_k	$E_e = 1\text{ mW/cm}^2$, $\lambda = 835\text{ nm}$	TK_{I_k}	-	0.1	-	%/K
Reverse light current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}	1.4	1.8	3	μA
	$E_e = 1\text{ mW/cm}^2$, $\lambda = 890\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}	-	2.6	-	μA
Angle of half sensitivity		ϕ	-	± 70	-	deg
Wavelength of peak sensitivity		λ_p	-	840	-	nm
Range of spectral bandwidth		$\lambda_{0.1}$	-	700 to 1070	-	nm
Rise time	$V_R = 5\text{ V}$, $R_L = 50\text{ }\Omega$, $\lambda = 820\text{ nm}$	t_r	-	60	-	ns
Fall time	$V_R = 5\text{ V}$, $R_L = 50\text{ }\Omega$, $\lambda = 820\text{ nm}$	t_f	-	80	-	ns

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Basic characteristics graphs to be extended to $110\text{ }^{\circ}\text{C}$ ambient temperatures where applicable.

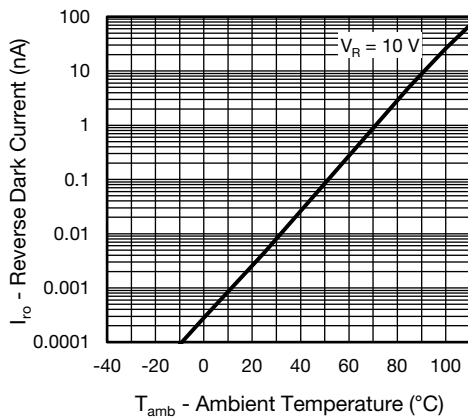


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

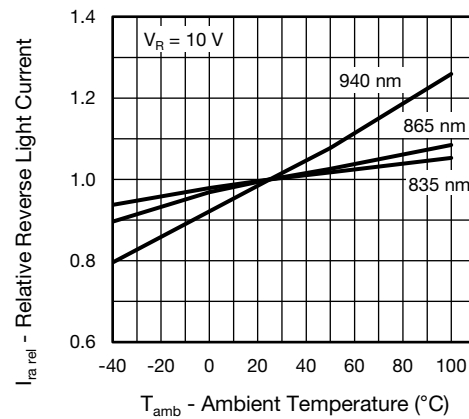


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

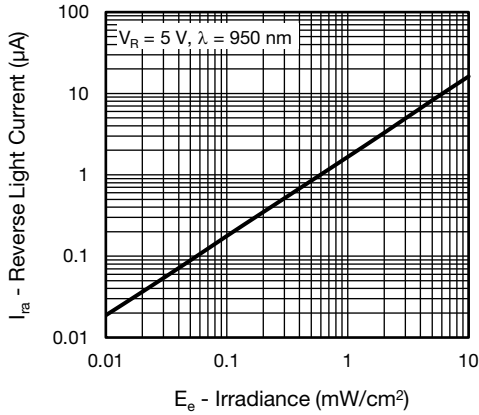


Fig. 3 - Reverse Light Current vs. Irradiance

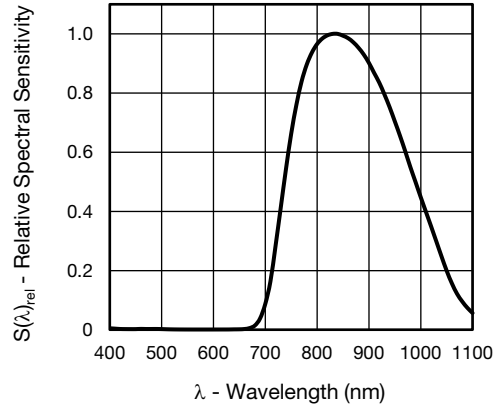


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

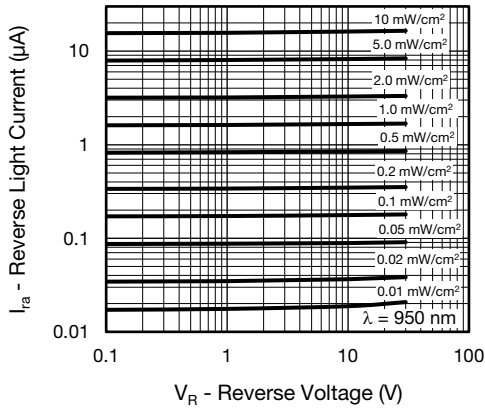


Fig. 4 - Reverse Light Current vs. Reverse Voltage

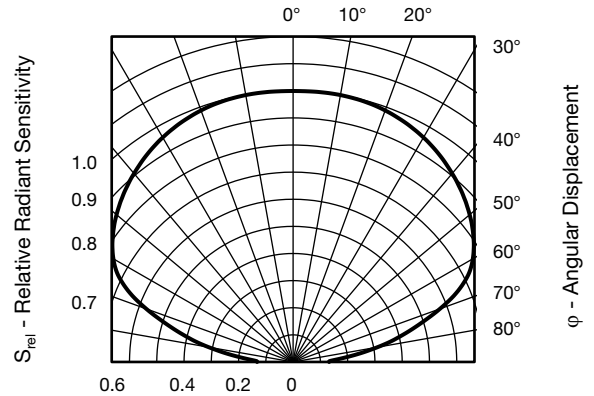


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

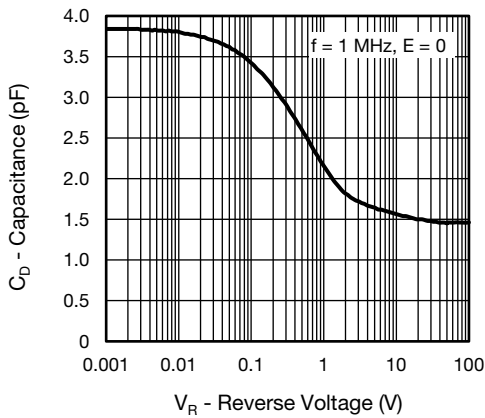


Fig. 5 - Diode Capacitance vs. Reverse Voltage

REFLOW SOLDER PROFILE

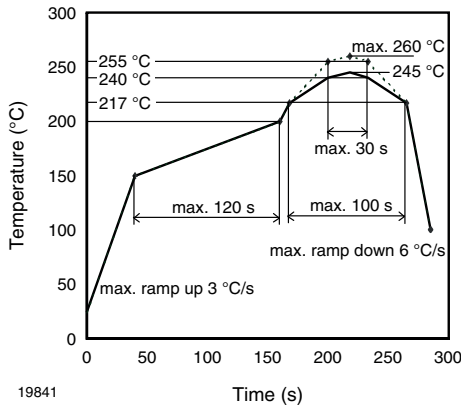


Fig. 8 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 72 h

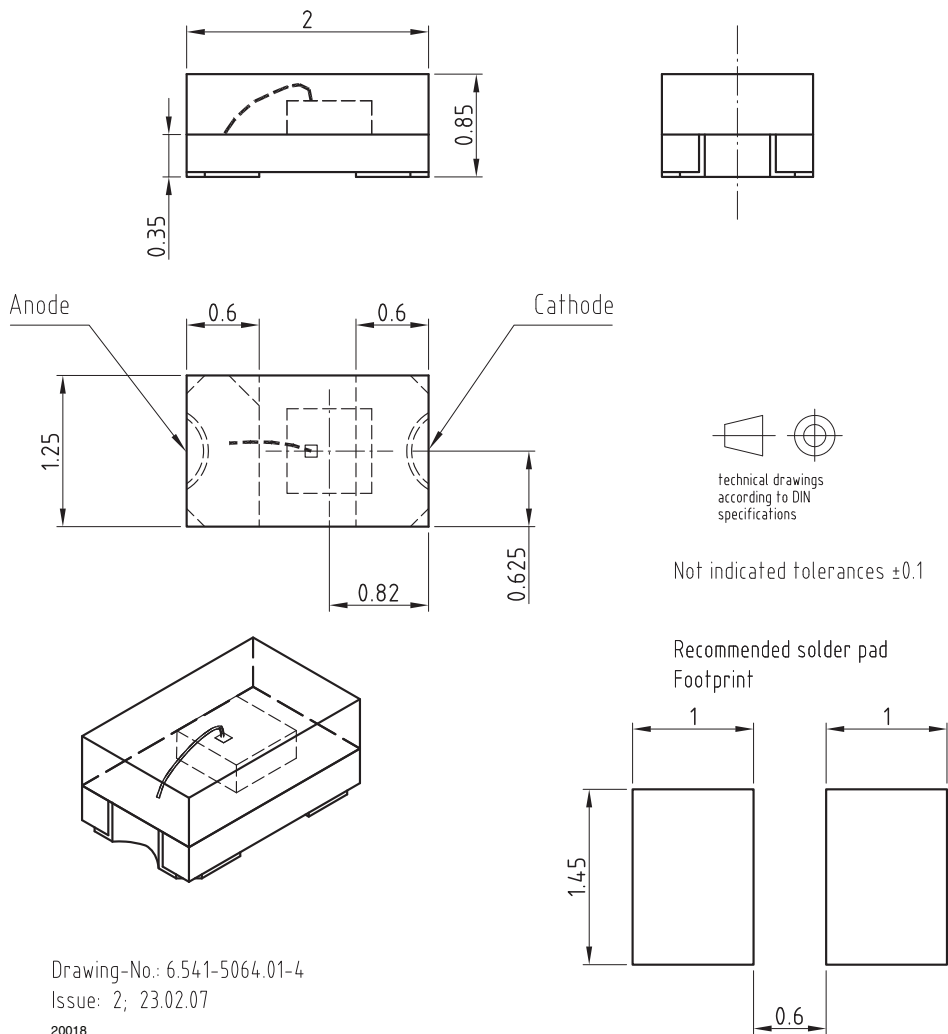
Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

Moisture sensitivity level 4, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

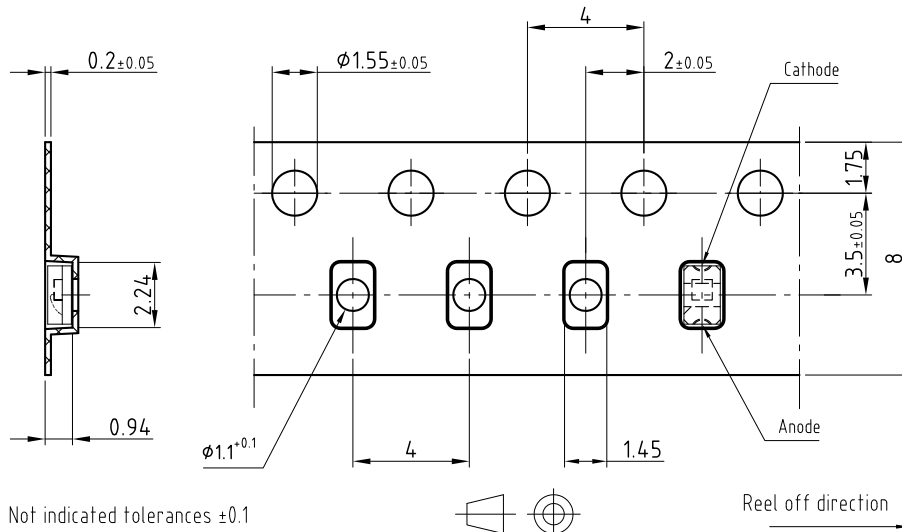
PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.541-5064.01-4
Issue: 2; 23.02.07
20018



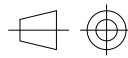
BLISTER TAPE DIMENSIONS in millimeters



Not indicated tolerances ± 0.1

Drawing-No.: 9.700-5311.01-4

Issue: 1; 23.02.07

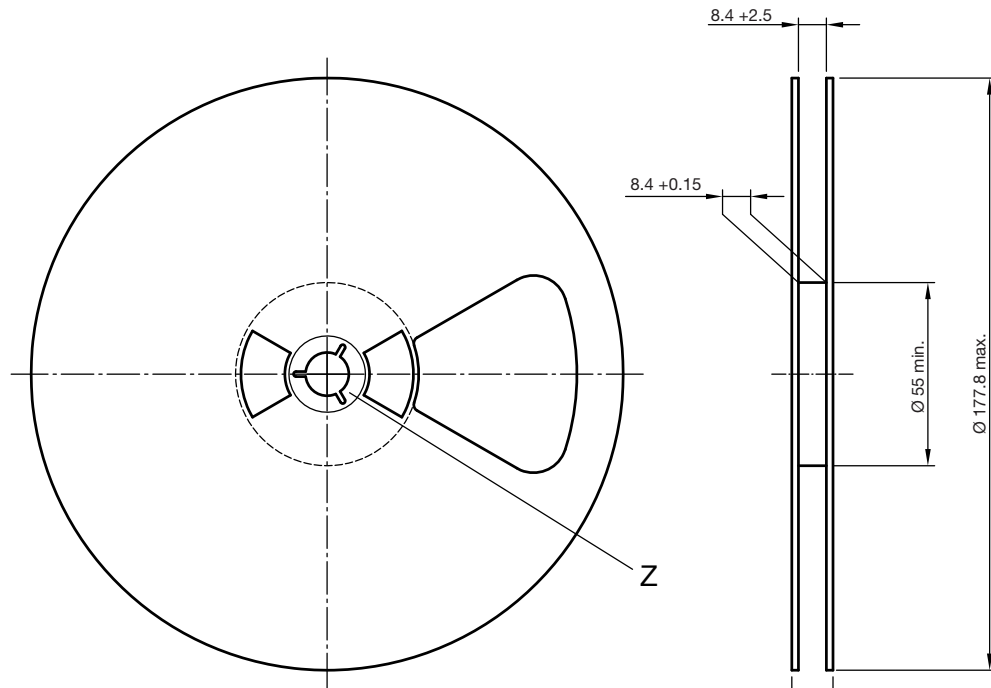


technical drawings according to DIN specifications

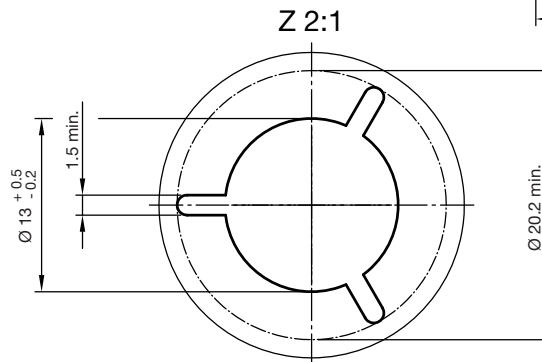
Reel off direction



REEL DIMENSIONS in millimeters



Form of the leave open
of the wheel is supplier specific.



technical drawings
according to DIN
specifications

Drawing-No.: 9.800-5096.01-4
Issue: 2; 26.04.10
20875



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